

# CX6SM AT CRYSTAL

9.6 MHz to 250 MHz **Ultra-Low Profile Miniature** Surface Mount AT Quartz Crystal

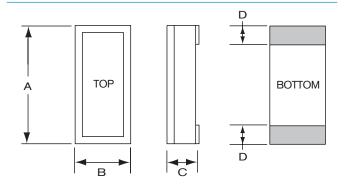
Fundamental Mode: 9.6 MHz - 250 MHz Third Overtone Mode: 48 MHz - 160 MHz

actual size

side view



# PACKAGE DIMENSIONS



	TYPICAL		MAXIMUM	
DIM	inches	mm	inches	mm
А	0.265	6.73	0.280	7.11
В	0.103	2.62	0.114	2.90
С	-	-	see below	
D	0.050	1.27	0.060	1.52

### THICKNESS (DIM C) MAXIMUM

	GLASS LID		CERAMIC LID	
	inches	mm	inches	mm
SM1	0.039	0.99	0.053	1.35
SM2/SM4	0.041	1.04	0.055	1.40
SM3/SM5	0.044	1.12	0.058	1.47

#### **DESCRIPTION**

STATEK's miniature CX6SM AT crystals in leadless ceramic packages are designed for surface mounting on printed circuit boards or hybrid substrates. These crystals have a small land pattern and a low profile. They are manufactured using the STATEK-developed photolithographic process, and were designed utilizing the experience acquired by producing millions of crystals for industrial, commercial, military and medical applications.

#### **FEATURES**

- Ultra low profile (less than 1 mm available) hermetically sealed ceramic package
- Designed for surface mount applications using infrared, vapor phase, or epoxy mount techniques.
- Excellent aging characteristics
- Available with glass or ceramic lid
- High shock and vibration resistance
- Custom designs available
- Full military testing available
- Designed and manufactured in the USA

#### **APPLICATIONS**

Medical

Monitoring Equipment

Industrial, Computer & Communications

- Down-hole Data Recorder
- Environmental Controls
- Handheld Inventory Control
- Telemetry

Military & Aerospace

- Communications
- Smart Munitions
- Timing Devices (Fuzes)
- Surveillance Devices

#### **SPECIFICATIONS**

Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice.

Fundamental Frequency	<u>10 MHz</u>	32 MHz	155.52 MHz
Motional Resistance $R_1$ ( $\Omega$ )	60	25	10
Motional Capacitance C <sub>1</sub> (fF)	2.8	6.2	4.0
Quality Factor Q (k)	95	30	30
Shunt Capacitance $C_0$ (pF)	1.4	2.3	2.3
Calibration Tolerance <sup>1</sup> Load Capacitance <sup>2</sup>	± 100 ppm, or tighter as required 20 pF for f ≤ 50 MHz 10 pF for f > 50 MHz		
Drive Level	500 μW	MAX for f	<ul><li>≤ 50 MHz</li><li>&gt; 50 MHz</li></ul>
Frequency-Temperature Stability <sup>1,3</sup>	± 50 ppm to ± 10 ppm (Commercial) ± 100 ppm to ± 20 ppm (Industrial) ± 100 ppm to ± 30 ppm (Military)		
Aging, first year <sup>3</sup>	5 ppm M	IAX (below 1	ppm available)
Shock, survival⁴	3,000 g, 0	0.3 ms, 1/	/2 sine
Vibration, survival <sup>5</sup>	20 g, 10-	-2,000 Hz	swept sine
Operating Temp. Range	$-40^{\circ}C$ to	+70°C ( +85°C ( +125°C (	•
Storage Temp. Range	-55°C to	+125°C	

1. Other tolerances available. Contact factory.

Max Process Temperature 260°C for 20 sec.

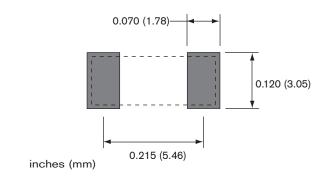
- 2. Unless specified otherwise.
- 3. Does not include calibration tolerance. The characteristics of the frequency stability over temperature follow that of the AT thickness-shear mode.
- $4.\ 10\ ppm\ MAX$  for frequencies below 40 MHz. For tighter tolerances and higher frequencies contact factory.
- 5. Higher shock version available.
- 6. Per MIL-STD-202G, Method 204D, Condition D. Random vibration testing also available.

#### **TERMINATIONS**

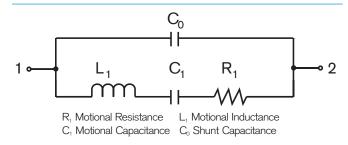
<u>Designation</u>	<u>Termination</u>
SM1	Gold Plated (Lead Free)
SM2	Solder Plated
SM3	Solder Dipped
SM4	Solder Plated (Lead Free)
SM5	Solder Dipped (Lead Free)

Max Process Temperature 260°C for 20 sec.

# SUGGESTED LAND PATTERN



#### **EQUIVALENT CIRCUIT**



## **PACKAGING**

- Tray Pack
- Tape and Reel Per EIA 481 (see Tape and Reel data sheet 10109)

## HOW TO ORDER CX6SM AT CRYSTALS

